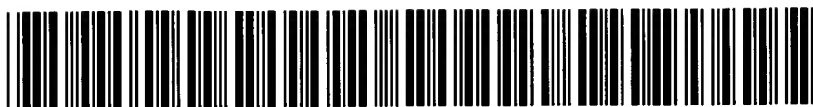


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7	BRS	433	(chip or die or IC or semiconductor) and heat near (spreader) and (dielectric or insulative)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
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	Type	Hits	Search Text	DBs
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12	BRS	653	361/\$.ccls. and (chip or die or IC or semiconductor) and heat near (transfer) and (dielectric or insulative)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	1	"6389689"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
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15	BRS	74	(257/690 or 257/706 or 257/707 or 257/720 or 257/778) and (chip or die or semiconductor) and substrate and solder adj mask and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	404	(257/779 or 257/780 or 257/782 or 257/783 or 257/784 or 257/786) and (chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

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84	BRS	1	"5849607".PN.	USPAT	2002/05/21 21:30
85	BRS	1	"5847929".PN.	USPAT	2002/05/21 21:30
86	BRS	1	"5840599".PN.	USPAT	2002/05/21 21:30
87	BRS	1	"5773313".PN.	USPAT	2002/05/21 21:31
88	BRS	1	"5729049".PN.	USPAT	2002/05/21 21:32
89	BRS	1	"5677566".PN.	USPAT	2002/05/21 21:32
90	BRS	1	"5674785".PN.	USPAT	2002/05/21 21:32
91	BRS	1	"5554886".PN.	USPAT	2002/05/21 21:32
92	BRS	1	"5483024".PN.	USPAT	2002/05/21 21:33
93	BRS	1	"5434105".PN.	USPAT	2002/05/21 21:33
94	BRS	1	"5418189".PN.	USPAT	2002/05/21 21:33
95	BRS	1	"5286679".PN.	USPAT	2002/05/21 21:33
96	BRS	1	"6326700"	USPAT	2002/05/21 22:21
97	BRS	1	"5977624".PN.	USPAT	2002/05/21 22:21
98	BRS	1	"6150730".PN.	USPAT	2002/05/21 22:21
99	BRS	1	"6177721".PN.	USPAT	2002/05/21 22:21
100	BRS	1	"6218731".PN.	USPAT	2002/05/21 22:21
101	BRS	1	"6252298".PN.	USPAT	2002/05/21 22:22
102	BRS	0	6071757.uref. and heat near sink and dielectric near (layer or film)	USPAT	2002/05/21 22:33
103	BRS	1	6071757.uref.	USPAT	2002/05/21 22:33
104	BRS	3	"6071757"	USPAT	2002/05/21 22:34
105	BRS	7	"5977629"	USPAT	2002/05/21 22:34



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